L Number	Hits	Search Text	DB	Time stamp
-	509414	semiconductor and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:15
-	1293	passive same interconnect$4 same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:15
-	135	trench same encircle$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:16
-	1	(semiconductor and substrate) and (passive same interconnect$4 same substrate) and (trench same encircle$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:16
-	1	(passive same interconnect$4 same substrate) and (trench same encircle$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:16
-	85	(semiconductor and substrate) and (trench same encircle$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:17
-	78	((semiconductor and substrate) and (trench same encircle$1)) and layer$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:17
-	30	(((semiconductor and substrate) and (trench same encircle$1)) and layer$1 and interconnect$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:17
-	27	((((semiconductor and substrate) and (trench same encircle$1)) and layer$1 and interconnect$4) and @ad<=20010418	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/15 13:18